HI1206N800R-10

UNCONTROLLED DOCUMENT

PHYSICAL DIMENSIONS:

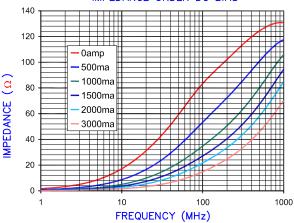
± 0.20 [.008] A 3.20 [.126]

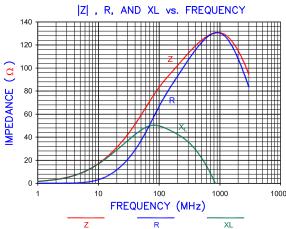
B 1.60 [.063] ± 0.20 [.008]

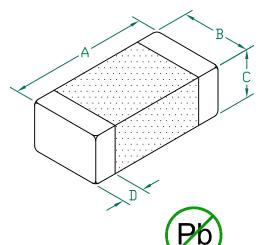
C 1.10 [.043] ± 0.20 [.008]

D 0.51 [.020] ± 0.25 [.010]

Z vs. FREQUENCY IMPEDANCE UNDER DC BIAS





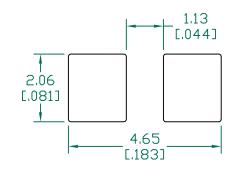


ELEC1	TRICAL CHARACTERISTICS:					
Z @ 100MHz (Ω)		DCR $\left(\begin{array}{c}\Omega\end{array}\right)$	Rated Current			
Nominal	80					
Minimum	60					
Maximum	100	0.035	3000 mA			

NOTES: UNLESS OTHERWISE SPECIFIED

- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL.
- 2. TERMINATION FINISH IS 100% TIN.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. OPERATEING TEMPERATURE TEMP: -40°C~+125°C (INCLUDING SELF-HEATING)

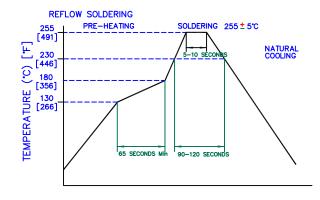
LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762 [0.030] to this dimension)

DESCRIPTION

RECOMMENDED SOLDERING CONDITIONS



HI1206N800R-10-D

DIMENSIONS ARE IN mm [INCHES].				This print is the property of Laird					-			
				Tech. and is loaned in confidence			_	= ,	7,			
				subject to return upon request with the understanding that no	Laird							
				copies shall be made without th								
				written consent of Laird Tech. A	_							
D	OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU	reserved.								
	OPDATE LAIRD LOGO AND REPLOW CORVE			PROJECT/PART NUMBER:	- 1	REV	PART TO	PE:	DRAWN BY:			
O	UPDATE COMPANY LOGO	06/15/09	JRK	HI1206N800R-10		D	00	FIDE	тмв			
В	ADD RoHS SYMBOL AND UPDATE	10/29/07	l				CO-FIRE		11110			
	COMPANY LOGO			PATE: 04/02/04	SCAL	E: N	rs	SHEET:	•			
Α	ORIGINAL DRAFT	04/02/04	тмв	200.4	TOOL		13	2	of 2			
				100 # HI1206NB00P_10_D			_	_	01 2			

DATE INT

AGILENT E4991A RF Impedance/Material Analyzer HP 16092A Test Fixture. TEST REF. 3298